

GaAs Infrared Emitting Diode in Miniature (T-3/4) Package

Description

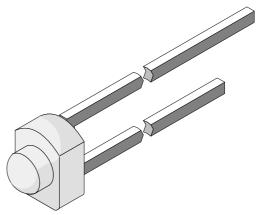
CQY37N is a standard GaAs infrared emitting diode in a miniature top view plastic package.

Its clear lens provides a high radiant intensity without external optics.

The diode is case compatible to the BPW17N phototransistor, allowing the user to assemble his own optical interrupters.

Features

- Suitable for pulse operation
- Standard T-3/4 lensed miniature package
- Angle of half intensity $\varphi = \pm 12^{\circ}$
- Peak wavelength $\lambda_p = 950 \text{ nm}$
- Good spectral matching to Si photodetectors



94 8639

Applications

Radiation source in near infrared range

Absolute Maximum Ratings

 $T_{amb} = 25^{\circ}C$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		V_{R}	5	V
Forward Current		I_{F}	100	mA
Surge Forward Current	$t_p \leq 100 \ \mu s$	I _{FSM}	2	A
Power Dissipation		P_{V}	170	mW
Junction Temperature		Tj	100	°C
Storage Temperature Range		T_{stg}	-25+100	°C
Soldering Temperature	$t \leq 3 s$	T_{sd}	245	°C
Thermal Resistance Junction/Ambient		R _{thJA}	450	K/W



Basic Characteristics

 $T_{amb}=25\,^{\circ}C$

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Forward Voltage	$I_F = 50 \text{ mA}, t_p \leq 20 \text{ms}$	$V_{\rm F}$		1.3	1.6	V
Breakdown Voltage	$I_R = 100 \mu A$	V _(BR)	5			V
Junction Capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0$	C _j		50		pF
Radiant Intensity	$I_F = 50 \text{ mA}, t_p \leq 20 \text{ ms}$	I _e	2.2	5		mW/sr
Radiant Power	$I_F = 50 \text{ mA}, t_p \leq 20 \text{ ms}$	фе		5		mW
Temp. Coefficient of φ _e	$I_F = 50 \text{ mA}$	TKφe		-0.8		%/K
Angle of Half Intensity		φ		±12		deg
Peak Wavelength	$I_F = 50 \text{ mA}$	λ_{p}		950		nm
Spectral Bandwidth	$I_F = 50 \text{ mA}$	Δλ		50		nm
Rise time	$I_F=1.5A$, $t_p/T=0.01$, $t_p \le 10 \mu s$	t _r		400		ns
Fall Time	$I_F=1.5A$, $t_p/T=0.01$, $t_p \le 10 \mu s$	t_{f}		450		ns

Typical Characteristics ($T_{amb} = 25^{\circ}C$ unless otherwise specified)

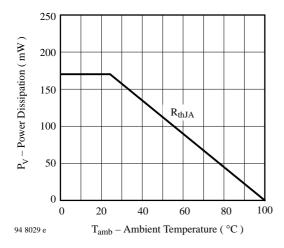


Figure 1. Power Dissipation vs. Ambient Temperature

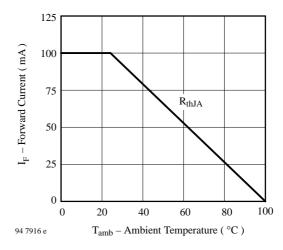


Figure 2. Forward Current vs. Ambient Temperature

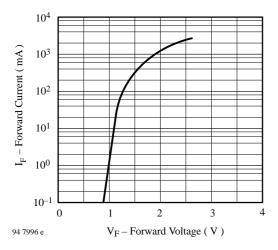


Figure 3. Forward Current vs. Forward Voltage

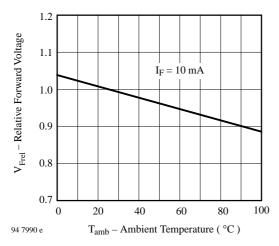


Figure 4. Relative Forward Voltage vs. Ambient Temperature

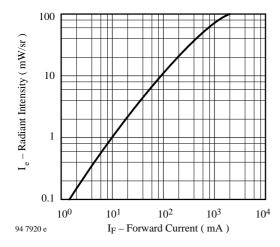


Figure 5. Radiant Intensity vs. Forward Current

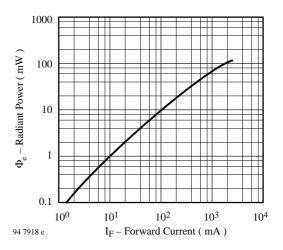


Figure 6. Radiant Power vs. Forward Current

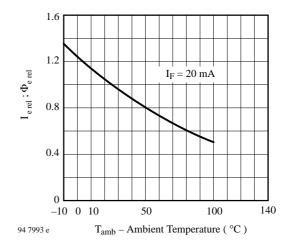


Figure 7. Rel. Radiant Intensity\Power vs. Ambient Temperature

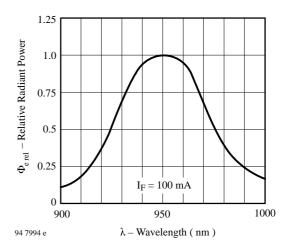


Figure 8. Relative Radiant Power vs. Wavelength

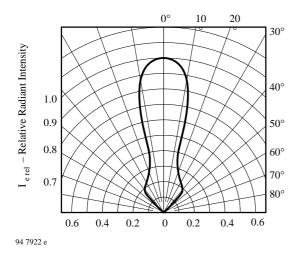
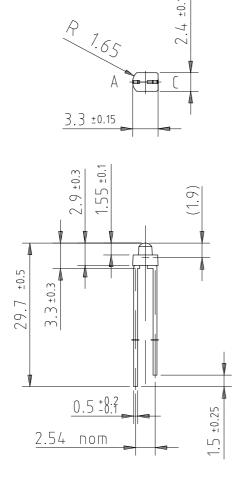
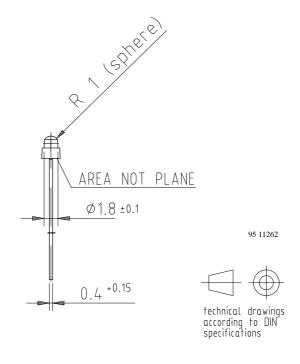


Figure 9. Relative Radiant Intensity vs. Angular Displacement

Dimensions in mm







Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

- 1. Meet all present and future national and international statutory requirements.
- Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423